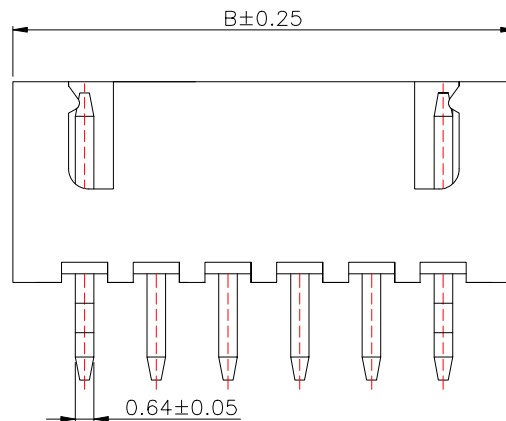


SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻:  $\leq 10\text{m}\Omega$
4. 绝缘电阻:  $\geq 100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度:  $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$  温度  $235\pm 5^{\circ}$ , 时间  $2.5\pm 0.5$  秒
10. 铅和镉等六大有害物质含量要符合环保要求。

| Part No            | Pin | A     | B     |
|--------------------|-----|-------|-------|
| WAFER-XH2.54-2PZZ  | 2   | 2.50  | 7.50  |
| WAFER-XH2.54-3PZZ  | 3   | 5.00  | 10.00 |
| WAFER-XH2.54-4PZZ  | 4   | 7.50  | 12.50 |
| WAFER-XH2.54-5PZZ  | 5   | 10.00 | 15.00 |
| WAFER-XH2.54-6PZZ  | 6   | 12.50 | 17.50 |
| WAFER-XH2.54-7PZZ  | 7   | 15.00 | 20.00 |
| WAFER-XH2.54-8PZZ  | 8   | 17.50 | 22.50 |
| WAFER-XH2.54-9PZZ  | 9   | 20.00 | 25.00 |
| WAFER-XH2.54-10PZZ | 10  | 22.50 | 27.50 |
| WAFER-XH2.54-11PZZ | 11  | 25.00 | 30.00 |
| WAFER-XH2.54-12PZZ | 12  | 27.50 | 32.50 |
| WAFER-XH2.54-13PZZ | 13  | 30.00 | 35.00 |
| WAFER-XH2.54-14PZZ | 14  | 32.50 | 37.50 |
| WAFER-XH2.54-15PZZ | 15  | 35.00 | 40.00 |
| WAFER-XH2.54-16PZZ | 16  | 37.50 | 42.50 |
| WAFER-XH2.54-17PZZ | 17  | 40.00 | 45.00 |
| WAFER-XH2.54-18PZZ | 18  | 42.50 | 47.50 |
| WAFER-XH2.54-19PZZ | 19  | 45.00 | 50.00 |
| WAFER-XH2.54-20PZZ | 20  | 47.50 | 52.50 |

| 2  | 端子Contact | 黄铜                | N*1 | 电镀(锡): 整个表面镀底镍<br>30u"MIN, 再镀锡80u"MIN |
|----|-----------|-------------------|-----|---------------------------------------|
| 1  | 基座Wafer   | PA66(UL94<br>V-0) | 1   | 白色                                    |
| 序号 | 名称        | 材料                | 数量  | 备注                                    |

MANUFACTURE DWG

东莞市讯普电子科技有限公司  
DongGuan XunPu Electronics Co., LtdUNLESS OTHERWISE  
SPECIFIED TOLERANCES

DECIMALS:

.X±0.20

.XX±0.10

.XXX±0.05

ANGLES:

±2°



TITLE:

WAFER XH2.54MM 直针

PAR

WAFER-XH2.54-NPZZ

DWN

CHKD

APVD

SCALE:1:1

UNIT:MM

SHEET:1F1

REV:A